Renesas Electronics America Inc - R5F2136ASNFP#30 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	59
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2136asnfp-30

1.4 Pin Assignment

Figure 1.3 shows Pin Assignment (Top View). Tables 1.4 to 1.6 list the Pin Name Information by Pin Number.

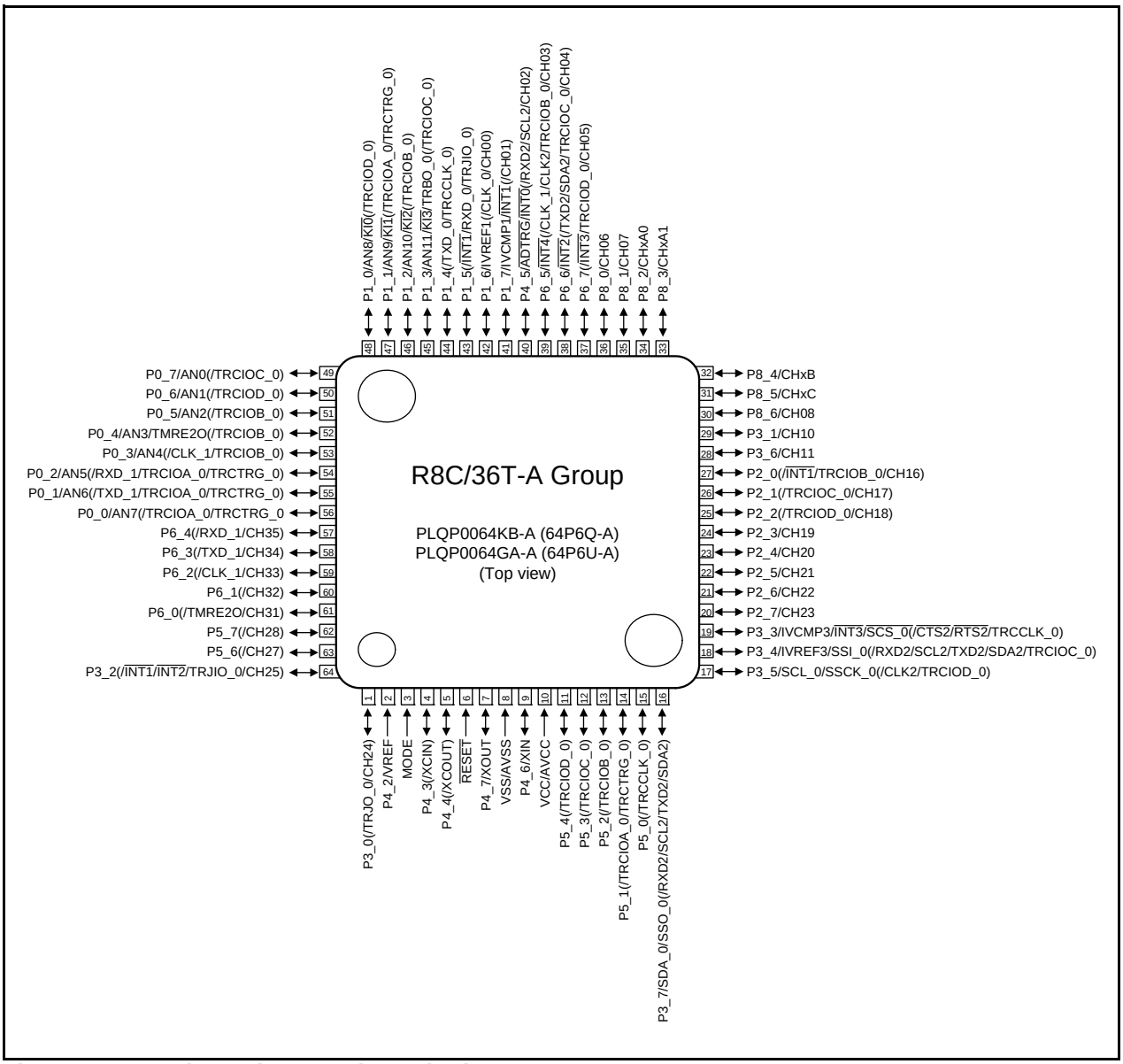


Figure 1.3 Pin Assignment (Top View)

1.5 Pin Functions

Tables 1.7 and 1.8 list Pin Functions.

Table 1.7 Pin Functions (1)

Item	Pin Name	I/O	Description
Power supply input	VCC, VSS	—	Apply 1.8 V through 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	—	Power supply input for the A/D converter. Connect a capacitor between pins AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Applying a low level to this pin resets the MCU.
MODE	MODE	I	Connect this pin to the VCC pin via a resistor.
XIN clock input	XIN	I	I/O for the XIN clock generation circuit. Connect a ceramic resonator or a crystal oscillator between pins XIN and XOUT. (1) To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XIN clock output	XOUT	I/O	
XCIN clock input	XCIN	I	I/O for the XCIN clock generation circuit. Connect a crystal oscillator between pins XCIN and XCOUT. (1) To use an external clock, input it to the XCOUT pin and leave the XCIN pin open.
XCIN clock output	XCOUT	I/O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT4}}$	I	$\overline{\text{INT}}$ interrupt input.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input.
Timer RJ_0	TRJIO_0	I/O	Input/output for timer RJ.
	TRJO_0	O	Output for timer RJ.
Timer RB2_0	TRBO_0	O	Output for timer RB2.
Timer RC_0	TRCCLK_0	I	External clock input.
	TRCTRG_0	I	External trigger input.
	TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0	I/O	Input/output for timer RC.
Timer RE2	TMRE2O	O	Divided clock output.
Serial interface (UART0)	CLK_0, CLK_1	I/O	Transfer clock input/output.
	RXD_0, RXD_1	I	Serial data input.
	TXD_0, TXD_1	O	Serial data output.
Serial interface (UART2)	$\overline{\text{CTS2}}$	I	Input for transmission control.
	$\overline{\text{RTS2}}$	O	Output for reception control.
	SCL2	I/O	I^2C mode clock input/output.
	SDA2	I/O	I^2C mode data input/output.
	RXD2	I	Serial data input.
	TXD2	O	Serial data output.
	CLK2	I/O	Transfer clock input/output.
Synchronous serial communication unit (SSU_0)	SSI_0	I/O	Data input/output.
	$\overline{\text{SCS\_0}}$	I/O	Chip-select input/output.
	$\overline{\text{SSCK\_0}}$	I/O	Clock input/output.
	SSO_0	I/O	Data input/output.
I^2C bus (I^2C_0)	SCL_0	I/O	Clock input/output.
	SDA_0	I/O	Data input/output.
Reference voltage input	VREF	I	Reference voltage input for the A/D converter.

Note:
1. Contact the oscillator manufacturer for oscillation characteristics.

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts. Interrupts are disabled when the I flag is 0, and are enabled when the I flag is 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is 0. USP is selected when the U flag is 1. The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction for a software interrupt numbered from 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns eight processor interrupt priority levels from 0 to 7. If a requested interrupt has higher priority than IPL, the interrupt is enabled.

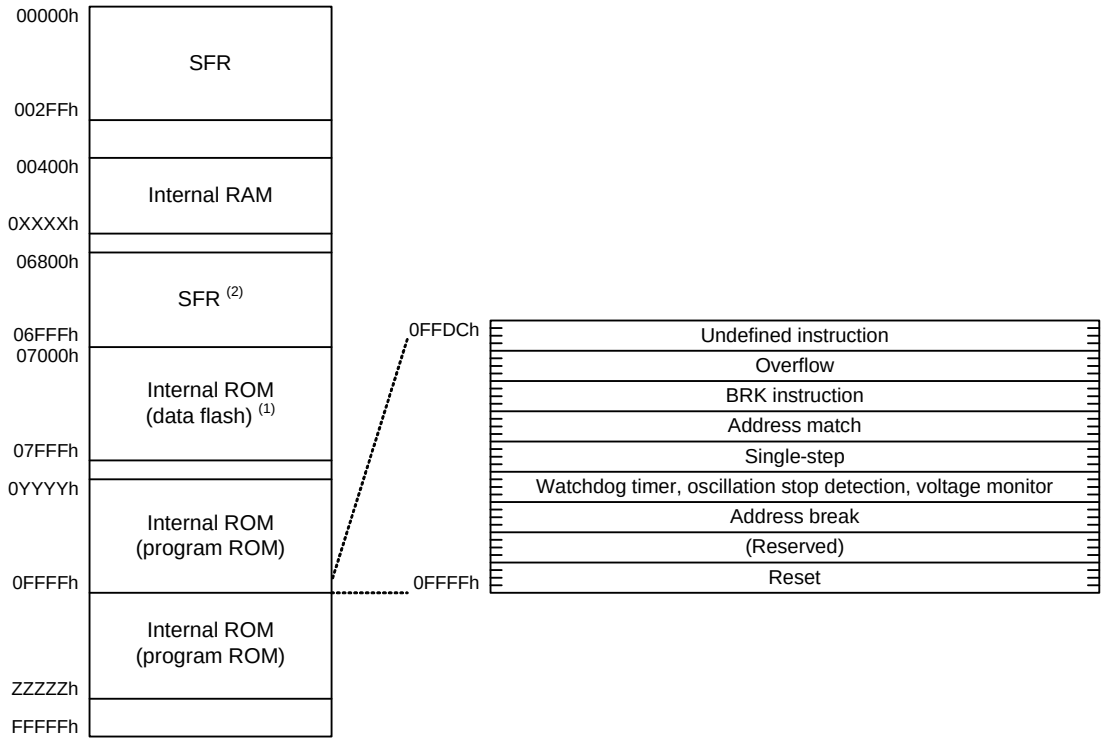
2.8.10 Reserved Bit

The write value must be 0. The read value is undefined.

3. Address Space

3.1 Memory Map

Figure 3.1 shows the Memory Map. The R8C/36T-A Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. Up to 32 Kbytes of the internal ROM (program ROM) is allocated at lower addresses, beginning with address 0FFFFh. The area in excess of 32 Kbytes is allocated at higher addresses, beginning with address 10000h. For example, a 64-Kbyte internal ROM is allocated at addresses 08000h to 17FFFh.
The fixed interrupt vector table is allocated at addresses 0FFDCh to 0FFFFh. The start address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated at addresses 07000h to 07FFFh.
The internal RAM is allocated at higher addresses, beginning with address 00400h. For example, a 6-Kbyte internal RAM is allocated at addresses 00400h to 01BFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated at addresses 00000h to 02FFFh and addresses 06800h to 06FFFh. Peripheral function control registers are allocated here. All unallocated locations within the SFRs are reserved and cannot be accessed by users.



Notes:
1. Data flash indicates block A (1 Kbyte), block B (1 Kbyte), block C (1 Kbyte), and block D (1 Kbyte).
2. Addresses 06800h to 06FFFh are used for the ELC, DTC, and TSCU SFR areas.
3. The blank areas are reserved. No access is allowed.

Part Number	Internal ROM			Internal RAM	
	Capacity	Address 0YYYYh	Address ZZZZZh	Capacity	Address 0XXXXh
R5F21368SNFP/FA, R5F21368SDFP/FA	64 Kbytes	08000h	17FFFh	6 Kbytes	01BFFh
R5F21368SNFP/FA, R5F21368SDFP/FA	96 Kbytes	08000h	1FFFFh	8 Kbytes	023FFh
R5F21368SNFP/FA, R5F21368SDFP/FA	128 Kbytes	08000h	27FFFh	10 Kbytes	02BFFh

Figure 3.1 Memory Map

3.2 Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 3.1 to 3.16 list the SFR Information. Table 3.17 lists the ID code Area, Option Function Select Area.

Table 3.1 SFR Information (1) (1)

Address	Symbol	Register Name	After Reset	Remarks
00000h				
00001h				
00002h				
00003h				
00004h	PM0	Processor Mode Register 0	00h	
00005h	PM1	Processor Mode Register 1	10000000b	
00006h				
00007h	PRCR	Protect Register	00h	
00008h	CM0	System Clock Control Register 0	00101000b	
00009h	CM1	System Clock Control Register 1	00100000b	
0000Ah	OCD	Oscillation Stop Detection Register	00h	
0000Bh	CM3	System Clock Control Register 3	00h	
0000Ch	CM4	System Clock Control Register 4	00000001b	
0000Dh				
0000Eh				
0000Fh				
00010h	CPSRF	Clock Prescaler Reset Flag	00h	
00011h				
00012h	FRA0	High-Speed On-Chip Oscillator Control Register 0	00h	
00013h				
00014h	FRA2	High-Speed On-Chip Oscillator Control Register 2	00h	
00015h				
00016h				
00017h				
00018h				
00019h				
0001Ah				
0001Bh				
0001Ch				
0001Dh				
0001Eh				
0001Fh				
00020h	RISR	Reset Interrupt Select Register	10000000b or 00000000b	(Note 2)
00021h	WDTR	Watchdog Timer Reset Register	FFh	
00022h	WDTS	Watchdog Timer Start Register	FFh	
00023h	WDTC	Watchdog Timer Control Register	01111111b	
00024h	CSPR	Count Source Protection Mode Register	10000000b or 00000000b	(Note 2)
00025h				
00026h				
00027h				
00028h	RSTFR	Reset Source Determination Register	00XXXXXXb	
00029h				
0002Ah				
0002Bh				
0002Ch	SVDC	STBY VDC Power Control Register	00h	
0002Dh				
0002Eh				
0002Fh				
00030h	CMPA	Voltage Monitor Circuit Control Register	00h	
00031h	VCAC	Voltage Monitor Circuit Edge Select Register	00h	
00032h	OCVREFCR	On-Chip Reference Voltage Control Register	00h	
00033h				
00034h	VCA2	Voltage Detection Register 2	00000000b or 00100000b	(Note 3)
00035h				
00036h	VD1LS	Voltage Detection 1 Level Select Register	00000111b	
00037h				
00038h	VW0C	Voltage Monitor 0 Circuit Control Register	1100XX10b or 1100XX11b	(Note 3)
00039h	VW1C	Voltage Monitor 1 Circuit Control Register	10001010b	

X: Undefined

Notes:

1. The blank areas are reserved. No access is allowed.
2. Depends on the CSPROINI bit in the OFS register.
3. Depends on the LVDASI bit in the OFS register.

Table 3.2 SFR Information (2) (1)

Address	Symbol	Register Name	After Reset	Remarks
0003Ah	VW2C	Voltage Monitor 2 Circuit Control Register	10001010b	
0003Bh				
0003Ch				
0003Dh				
0003Eh				
0003Fh				
00040h				
00041h	FMRDYIC	Interrupt Control Register	00h	
00042h				
00043h				
00044h				
00045h				
00046h	INT4IC	Interrupt Control Register	00h	
00047h	TRCIC_0	Interrupt Control Register	00h	
00048h				
00049h				
0004Ah	TRE2IC	Interrupt Control Register	00h	
0004Bh	U2TIC	Interrupt Control Register	00h	
0004Ch	U2RIC	Interrupt Control Register	00h	
0004Dh	KUPIC	Interrupt Control Register	00h	
0004Eh	ADIC	Interrupt Control Register	00h	
0004Fh	SSUIC_0/IICIC_0	Interrupt Control Register	00h	
00050h				
00051h	U0TIC_0	Interrupt Control Register	00h	
00052h	U0RIC_0	Interrupt Control Register	00h	
00053h	U0TIC_1	Interrupt Control Register	00h	
00054h	U0RIC_1	Interrupt Control Register	00h	
00055h	INT2IC	Interrupt Control Register	00h	
00056h	TRJIC_0	Interrupt Control Register	00h	
00057h				
00058h	TRB2IC_0	Interrupt Control Register	00h	
00059h	INT1IC	Interrupt Control Register	00h	
0005Ah	INT3IC	Interrupt Control Register	00h	
0005Bh				
0005Ch				
0005Dh	INT0IC	Interrupt Control Register	00h	
0005Eh	U2BCNIC	Interrupt Control Register	00h	
0005Fh				
00060h				
00061h				
00062h				
00063h				
00064h				
00065h				
00066h				
00067h				
00068h				
00069h				
0006Ah				
0006Bh				
0006Ch				
0006Dh				
0006Eh				
0006Fh				
00070h				
00071h				
00072h	VCMP1IC	Interrupt Control Register	00h	
00073h	VCMP2IC	Interrupt Control Register	00h	
00074h				
00075h	TSCUIC	Interrupt Control Register	00h	
00076h				
00077h				
00078h				
00079h				

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.13 SFR Information (13) (1)

Address	Symbol	Register Name	After Reset	Remarks
06C0Ah		Area for storing DTC transfer vector 10	XXh	
06C0Bh		Area for storing DTC transfer vector 11	XXh	
06C0Ch		Area for storing DTC transfer vector 12	XXh	
06C0Dh		Area for storing DTC transfer vector 13	XXh	
06C0Eh		Area for storing DTC transfer vector 14	XXh	
06C0Fh		Area for storing DTC transfer vector 15	XXh	
06C10h		Area for storing DTC transfer vector 16	XXh	
06C11h		Area for storing DTC transfer vector 17	XXh	
06C12h		Area for storing DTC transfer vector 18	XXh	
06C13h		Area for storing DTC transfer vector 19	XXh	
06C14h				
06C15h				
06C16h		Area for storing DTC transfer vector 22	XXh	
06C17h		Area for storing DTC transfer vector 23	XXh	
06C18h		Area for storing DTC transfer vector 24	XXh	
06C19h		Area for storing DTC transfer vector 25	XXh	
06C1Ah				
06C1Bh				
06C1Ch				
06C1Dh				
06C1Eh				
06C1Fh				
06C20h				
06C21h				
06C22h				
06C23h				
06C24h				
06C25h				
06C26h				
06C27h				
06C28h				
06C29h				
06C2Ah		Area for storing DTC transfer vector 42	XXh	
06C2Bh				
06C2Ch				
06C2Dh				
06C2Eh				
06C2Fh				
06C30h				
06C31h		Area for storing DTC transfer vector 49	XXh	
06C32h				
06C33h		Area for storing DTC transfer vector 51	XXh	
06C34h		Area for storing DTC transfer vector 52	XXh	
06C35h		Area for storing DTC transfer vector 53	XXh	
06C36h		Area for storing DTC transfer vector 54	XXh	
06C37h				
06C38h				
06C39h				
06C3Ah				
06C3Bh				
06C3Ch				
06C3Dh				
06C3Eh				
06C3Fh				
06C40h	DTCCR0	DTC Control Register 0	XXh	
06C41h	DTBLS0	DTC Block Size Register 0	XXh	
06C42h	DTCCT0	DTC Transfer Count Register 0	XXh	
06C43h	DTRLD0	DTC Transfer Count Reload Register 0	XXh	
06C44h	DTSAR0	DTC Source Address Register 0	XXXXh	
06C45h				
06C46h	DTDAR0	DTC Destination Address Register 0	XXXXh	
06C47h				
06C48h	DTCCR1	DTC Control Register 1	XXh	
06C49h	DTBLS1	DTC Block Size Register 1	XXh	

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.14 SFR Information (14) (1)

Address	Symbol	Register Name	After Reset	Remarks
06C4Ah	DTCCT1	DTC Transfer Count Register 1	XXh	
06C4Bh	DTRLD1	DTC Transfer Count Reload Register 1	XXh	
06C4Ch	DTSAR1	DTC Source Address Register 1	XXXXh	
06C4Dh				
06C4Eh	DTDAR1	DTC Destination Address Register 1	XXXXh	
06C4Fh				
06C50h	DTCCR2	DTC Control Register 2	XXh	
06C51h	DTBLS2	DTC Block Size Register 2	XXh	
06C52h	DTCCT2	DTC Transfer Count Register 2	XXh	
06C53h	DTRLD2	DTC Transfer Count Reload Register 2	XXh	
06C54h	DTSAR2	DTC Source Address Register 2	XXXXh	
06C55h				
06C56h	DTDAR2	DTC Destination Address Register 2	XXXXh	
06C57h				
06C58h	DTCCR3	DTC Control Register 3	XXh	
06C59h	DTBLS3	DTC Block Size Register 3	XXh	
06C5Ah	DTCCT3	DTC Transfer Count Register 3	XXh	
06C5Bh	DTRLD3	DTC Transfer Count Reload Register 3	XXh	
06C5Ch	DTSAR3	DTC Source Address Register 3	XXXXh	
06C5Dh				
06C5Eh	DTDAR3	DTC Destination Address Register 3	XXXXh	
06C5Fh				
06C60h	DTCCR4	DTC Control Register 4	XXh	
06C61h	DTBLS4	DTC Block Size Register 4	XXh	
06C62h	DTCCT4	DTC Transfer Count Register 4	XXh	
06C63h	DTRLD4	DTC Transfer Count Reload Register 4	XXh	
06C64h	DTSAR4	DTC Source Address Register 4	XXXXh	
06C65h				
06C66h	DTDAR4	DTC Destination Address Register 4	XXXXh	
06C67h				
06C68h	DTCCR5	DTC Control Register 5	XXh	
06C69h	DTBLS5	DTC Block Size Register 5	XXh	
06C6Ah	DTCCT5	DTC Transfer Count Register 5	XXh	
06C6Bh	DTRLD5	DTC Transfer Count Reload Register 5	XXh	
06C6Ch	DTSAR5	DTC Source Address Register 5	XXXXh	
06C6Dh				
06C6Eh	DTDAR5	DTC Destination Address Register 5	XXXXh	
06C6Fh				
06C70h	DTCCR6	DTC Control Register 6	XXh	
06C71h	DTBLS6	DTC Block Size Register 6	XXh	
06C72h	DTCCT6	DTC Transfer Count Register 6	XXh	
06C73h	DTRLD6	DTC Transfer Count Reload Register 6	XXh	
06C74h	DTSAR6	DTC Source Address Register 6	XXXXh	
06C75h				
06C76h	DTDAR6	DTC Destination Address Register 6	XXXXh	
06C77h				
06C78h	DTCCR7	DTC Control Register 7	XXh	
06C79h	DTBLS7	DTC Block Size Register 7	XXh	
06C7Ah	DTCCT7	DTC Transfer Count Register 7	XXh	
06C7Bh	DTRLD7	DTC Transfer Count Reload Register 7	XXh	
06C7Ch	DTSAR7	DTC Source Address Register 7	XXXXh	
06C7Dh				
06C7Eh	DTDAR7	DTC Destination Address Register 7	XXXXh	
06C7Fh				
06C80h	DTCCR8	DTC Control Register 8	XXh	
06C81h	DTBLS8	DTC Block Size Register 8	XXh	
06C82h	DTCCT8	DTC Transfer Count Register 8	XXh	
06C83h	DTRLD8	DTC Transfer Count Reload Register 8	XXh	
06C84h	DTSAR8	DTC Source Address Register 8	XXXXh	
06C85h				
06C86h	DTDAR8	DTC Destination Address Register 8	XXXXh	
06C87h				
06C88h	DTCCR9	DTC Control Register 9	XXh	
06C89h	DTBLS9	DTC Block Size Register 9	XXh	
06C8Ah	DTCCT9	DTC Transfer Count Register 9	XXh	
06C8Bh	DTRLD9	DTC Transfer Count Reload Register 9	XXh	
06C8Ch	DTSAR9	DTC Source Address Register 9	XXXXh	
06C8Dh				
06C8Eh	DTDAR9	DTC Destination Address Register 9	XXXXh	
06C8Fh				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.16 SFR Information (16) (1)

Address	Symbol	Register Name	After Reset	Remarks
06CD0h	DTCCR18	DTC Control Register 18	XXh	
06CD1h	DTBLS18	DTC Block Size Register 18	XXh	
06CD2h	DTCCT18	DTC Transfer Count Register 18	XXh	
06CD3h	DTRLD18	DTC Transfer Count Reload Register 18	XXh	
06CD4h	DTSAR18	DTC Source Address Register 18	XXXXh	
06CD5h				
06CD6h	DTDAR18	DTC Destination Address Register 18	XXXXh	
06CD7h				
06CD8h	DTCCR19	DTC Control Register 19	XXh	
06CD9h	DTBLS19	DTC Block Size Register 19	XXh	
06CDAh	DTCCT19	DTC Transfer Count Register 19	XXh	
06CDBh	DTRLD19	DTC Transfer Count Reload Register 19	XXh	
06CDCh	DTSAR19	DTC Source Address Register 19	XXXXh	
06CDDh				
06CDEh	DTDAR19	DTC Destination Address Register 19	XXXXh	
06CDFh				
06CE0h	DTCCR20	DTC Control Register 20	XXh	
06CE1h	DTBLS20	DTC Block Size Register 20	XXh	
06CE2h	DTCCT20	DTC Transfer Count Register 20	XXh	
06CE3h	DTRLD20	DTC Transfer Count Reload Register 20	XXh	
06CE4h	DTSAR20	DTC Source Address Register 20	XXXXh	
06CE5h				
06CE6h	DTDAR20	DTC Destination Address Register 20	XXXXh	
06CE7h				
06CE8h	DTCCR21	DTC Control Register 21	XXh	
06CE9h	DTBLS21	DTC Block Size Register 21	XXh	
06CEAh	DTCCT21	DTC Transfer Count Register 21	XXh	
06CEBh	DTRLD21	DTC Transfer Count Reload Register 21	XXh	
06CECh	DTSAR21	DTC Source Address Register 21	XXXXh	
06CEDh				
06CEEh	DTDAR21	DTC Destination Address Register 21	XXXXh	
06CEFh				
06CF0h	DTCCR22	DTC Control Register 22	XXh	
06CF1h	DTBLS22	DTC Block Size Register 22	XXh	
06CF2h	DTCCT22	DTC Transfer Count Register 22	XXh	
06CF3h	DTRLD22	DTC Transfer Count Reload Register 22	XXh	
06CF4h	DTSAR22	DTC Source Address Register 22	XXXXh	
06CF5h				
06CF6h	DTDAR22	DTC Destination Address Register 22	XXXXh	
06CF7h				
06CF8h	DTCCR23	DTC Control Register 23	XXh	
06CF9h	DTBLS23	DTC Block Size Register 23	XXh	
06CFAh	DTCCT23	DTC Transfer Count Register 23	XXh	
06CFBh	DTRLD23	DTC Transfer Count Reload Register 23	XXh	
06CFCh	DTSAR23	DTC Source Address Register 23	XXXXh	
06CFDh				
06CFEh	DTDAR23	DTC Destination Address Register 23	XXXXh	
06CFFh				
06D00h to 06FFFh				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.17 ID code Area, Option Function Select Area

Address	Symbol	Area Name	After Reset	Address size
:				
0FFDBh	OFS2	Option Function Select Register 2	(Note 1)	
:				
0FFDFh	ID1		(Note 2)	
:				
0FFE3h	ID2		(Note 2)	
:				
0FFEBh	ID3		(Note 2)	
:				
0FFEFh	ID4		(Note 2)	
:				
0FFF3h	ID5		(Note 2)	
:				
0FFF7h	ID6		(Note 2)	
:				
0FFFBh	ID7		(Note 2)	
:				
0FFFFh	OFS	Option Function Select Register	(Note 1)	

Notes:
1. The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not perform any additional writes to the option function select area. Erasing the block including the option function select area sets the option function select area to FFh.
2. The ID code area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not perform any additional writes to the ID code area. Erasing the block including the ID code area sets the ID code area to FFh.

4. Electrical Characteristics

4.1 Absolute Maximum Ratings

Table 4.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
Vcc/AVcc ICEVcc	Supply voltage		–0.3 to 6.5	V
V_I	Input voltage		–0.3 to Vcc + 0.3	V
V_O	Output voltage		–0.3 to Vcc + 0.3	V
P_d	Power dissipation	–40°C ≤ Topr ≤ 85°C	500	mW
T_{opr}	Operating ambient temperature		–20 to 85 (N version)/ –40 to 85 (D version)	°C
T_{stg}	Storage temperature		–65 to 150	°C

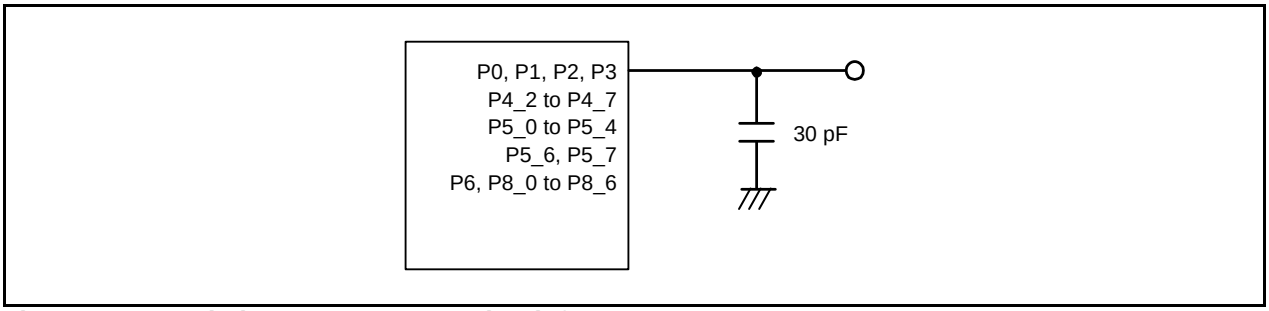


Figure 4.1 Timing Measurement Circuit for Ports P0, P1, P2, P3, P4_2 to P4_7, P5_0 to P5_4, P5_6, P5_7, P6, and P8_0 to P8_6

Table 4.6 Flash Memory (Data flash Block A to Block D) Characteristics (Vcc = 2.7 V to 5.5 V, Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		10,000 (2)	—	—	times
—	Byte program time (Program and erase endurance ≤ 1,000 times)		—	160	950	µs
—	Byte program time (Program and erase endurance > 1,000 times)		—	300	950	µs
—	Block erase time (Program and erase endurance ≤ 1,000 times)		—	0.2	1	s
—	Block erase time (Program and erase endurance > 1,000 times)		—	0.3	1	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	3 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	µs
—	Time from suspend until erase restart		—	—	30 + CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30 + CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		–20 (N ver.) –40 (D ver.)	—	85	°C
—	Data hold time (6)	Ambient temperature = 55°C (7)	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 100, 1,000 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A to D can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.
7. The data hold time includes 7,000 hours under an environment of ambient temperature 85°C.

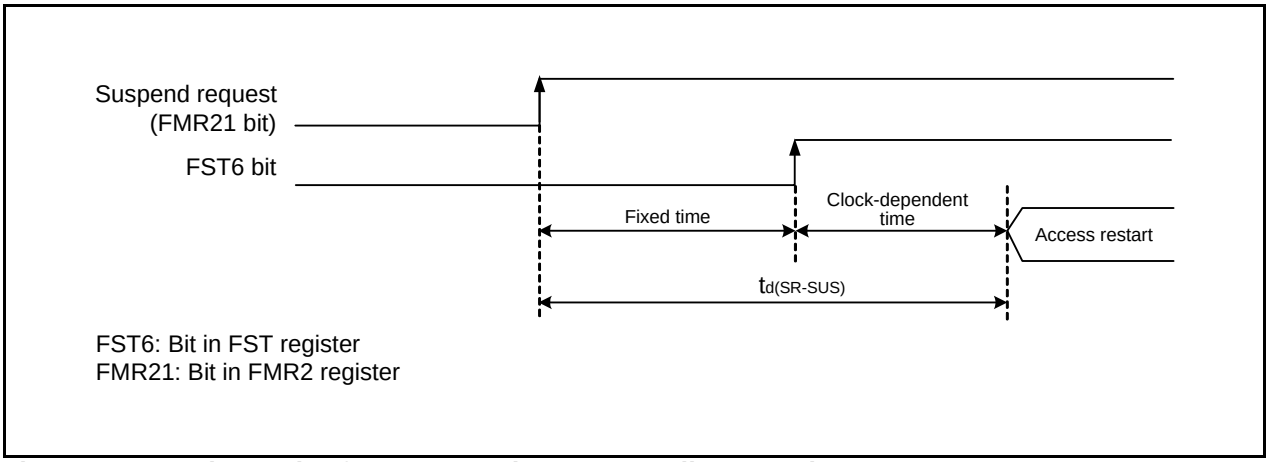


Figure 4.2 Time Delay from Suspend Request until Suspend

Table 4.7 Voltage Detection 0 Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

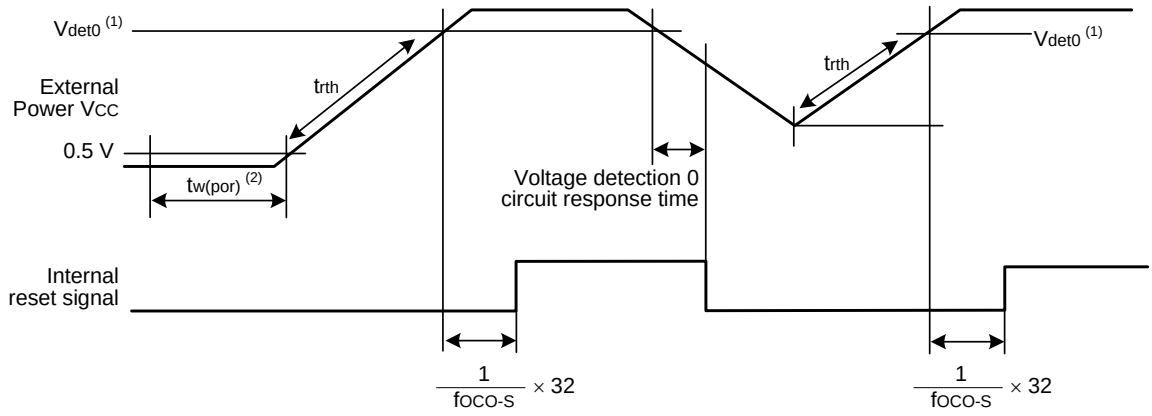
Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{det0}	Voltage detection level Vdet0_0 (1)	When Vcc falls	1.80	1.90	2.05	V
	Voltage detection level Vdet0_1 (1)	When Vcc falls	2.15	2.35	2.55	V
	Voltage detection level Vdet0_2 (1)	When Vcc falls	2.70	2.85	3.05	V
	Voltage detection level Vdet0_3 (1)	When Vcc falls	3.55	3.80	4.05	V
—	Voltage detection 0 circuit response time (2)	At the falling of Vcc from 5 V to (Vdet0 – 0.1) V	—	6	150	µs
—	Voltage detection circuit self power consumption	VCA25 = 1, Vcc = 5.0 V	—	1.5	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (3)		—	—	100	µs

Notes:
1. The voltage detection level must be selected with bits VDSEL0 and VDSEL1 in the OFS register.
2. Time until the voltage monitor 0 reset is generated after the voltage passes V_{det0}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA25 bit in the VCA2 register to 0.

Table 4.10 Power-On Reset Circuit Characteristics (1)
(Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
t_{rth}	External power VCC rise gradient		0	—	50,000	mV/msec

Note:
1. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS register to 0.



Notes:
1. V_{det0} indicates the voltage detection level of the voltage detection 0 circuit. Refer to the **Voltage Detection Circuit** chapter of User's Manual: Hardware for details.
2. $t_{w(por)}$ indicates the duration the external power Vcc must be held below the valid voltage (0.5 V) to enable a power-on reset. When turning on the power after it falls with voltage monitor 0 reset disabled, maintain $t_{w(por)}$ for 1 ms or more.

Figure 4.3 Power-on Reset Circuit Characteristics

Table 4.11 High-Speed On-Chip Oscillator Circuit Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	High-speed on-chip oscillator frequency after reset	Vcc = 1.8 V to 5.5 V, –20°C ≤ Topr ≤ 85°C (N version) –40°C ≤ Topr ≤ 85°C (D version)	—	40	—	MHz
	High-speed on-chip oscillator frequency when 01b or 10b is written to bits FRA25 and FRA24 in the FRA2 register (1)		—	36.864	—	MHz
	High-speed on-chip oscillator frequency when 10b is written to bits FRA25 and FRA24 in the FRA2 register		—	32	—	MHz
	High-speed on-chip oscillator frequency dependence on temperature and power supply voltage (2)		– 1.5	—	1.5	%
—	Oscillation stability time	Vcc = 5.0 V, Topr = 25°C	—	250	—	µs
—	Self power consumption at oscillation	Vcc = 5.0 V, Topr = 25°C	—	500	—	µA

Notes:
1. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.
2. This indicates the precision error for the oscillation frequency of the high-speed on-chip oscillator.

4.4 DC Characteristics

Table 4.14 DC Characteristics (1) [4.2 V ≤ Vcc ≤ 5.5 V] (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output high voltage	Other than XOUT	Drive capacity is high	I_{OH} = –20 mA	Vcc – 2.0	—	Vcc	V
			Drive capacity is low	I_{OH} = –5 mA	Vcc – 2.0	—	Vcc	V
				I_{OH} = –200 µA	Vcc – 0.3	—	Vcc	V
		XOUT		I_{OH} = –200 µA	1.0	—	Vcc	V
V_{OL}	Output low voltage	Other than XOUT	Drive capacity is high	I_{OL}= 20 mA	—	—	2.0	V
			Drive capacity is low	I_{OL} = 5 mA	—	—	2.0	V
				I_{OL} = 200 µA	—	—	0.45	V
		XOUT		I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$ to $\overline{INT4}$, $\overline{KI0}$ to $\overline{KI3}$, TRJIO_0, TRCCLK_0, TRCTRG_0, TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0, CLK_0, CLK_1, $\overline{RXD\_0}$, RXD_1, $\overline{CTS2}$, SCL2, SDA2, CLK2, RXD2, $\underline{SCL\_0}$, SDA_0, SSI_0, $\overline{SCS\_0}$, SSCK_0, SSO_0			0.1	1.2	—	V
		$\overline{RESET}$	Vcc = 5.0 V		0.1	1.2	—	V
I_{IH}	Input high current		V_I = 5.0 V		—	—	1.0	µA
I_{IL}	Input low current		V_I = 0 V		—	—	–1.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V		25	50	100	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Table 4.16 DC Characteristics (3) [2.7 V ≤ Vcc < 4.2 V]
(Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output high voltage	Other than XOUT	Drive capacity is high	I_{OH} = –5 mA	Vcc – 0.5	—	Vcc	V
			Drive capacity is low	I_{OH} = –1 mA	Vcc – 0.5	—	Vcc	V
		XOUT		I_{OH} = –200 µA	1.0	—	Vcc	V
V_{OL}	Output low voltage	Other than XOUT	Drive capacity is high	I_{OL} = 5 mA	—	—	0.5	V
			Drive capacity is low	I_{OL} = 1 mA	—	—	0.5	V
		XOUT		I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$ to $\overline{INT4}$, $\overline{KI0}$ to $\overline{KI3}$, TRJIO_0, TRCCLK_0, TRCTRG_0, TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0, CLK_0, CLK_1, RXD_0, RXD_1, $\overline{CTS2}$, SCL2, SDA2, CLK2, RXD2, $\underline{SCL\_0}$, SDA_0, SSI_0, $\overline{SCS\_0}$, SSCK_0, SSO_0			0.1	0.4	—	V
		$\overline{RESET}$	Vcc = 3.0 V		0.1	0.5	—	V
I_{IH}	Input high current		V_I = 3.0 V		—	—	1.0	µA
I_{IL}	Input low current		V_I = 0 V		—	—	–1.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V		42	84	168	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Table 4.18 DC Characteristics (5) [1.8 V ≤ Vcc < 2.7 V]
(Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output high voltage	Other than XOUT	Drive capacity is high	I_{OH} = –2 mA	Vcc – 0.5	—	Vcc	V
			Drive capacity is low	I_{OH} = –1 mA	Vcc – 0.5	—	Vcc	V
		XOUT		I_{OH} = –200 µA	1.0	—	Vcc	V
V_{OL}	Output low voltage	Other than XOUT	Drive capacity is high	I_{OL} = 2 mA	—	—	0.5	V
			Drive capacity is low	I_{OL} = 1 mA	—	—	0.5	V
		XOUT		I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$ to $\overline{INT4}$, $\overline{KI0}$ to $\overline{KI3}$, TRJIO_0, TRCCLK_0, TRCTRG_0, TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0, CLK_0, CLK_1, $\overline{RXD\_0}$, RXD_1,$\overline{CTS2}$, SCL2, SDA2, CLK2, RXD2, $\overline{SCL\_0}$, SDA_0,SSI_0, $\overline{SCS\_0}$, SSCK_0,SSO_0			0.05	0.2	—	V
		$\overline{RESET}$	V_{CC} = 2.2 V		0.05	0.2	—	V
I_{IH}	Input high current		V_I = 2.2 V		—	—	1.0	µA
I_{IL}	Input low current		V_I = 0 V		—	—	–1.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V		100	200	400	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Table 4.22 External Clock Input (XOUT, XCIN)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	200	—	50	—	50	—	ns
$t_{WH(XOUT)}$	XOUT input high width	90	—	24	—	24	—	ns
$t_{WL(XOUT)}$	XOUT input low width	90	—	24	—	24	—	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	—	14	—	14	—	µs
$t_{WH(XCIN)}$	XCIN input high width	7	—	7	—	7	—	µs
$t_{WL(XCIN)}$	XCIN input low width	7	—	7	—	7	—	µs

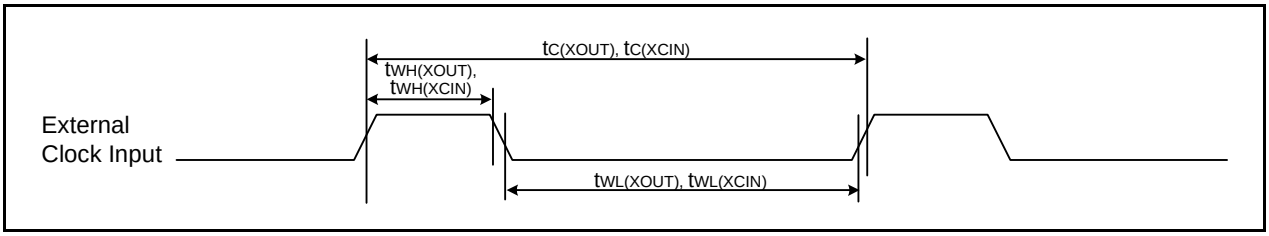


Figure 4.7 External Clock Input Timing Diagram

Table 4.23 Timing Requirements of TRJIO

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(TRJIO)}$	TRJIO input cycle time	500	—	300	—	100	—	ns
$t_{WH(TRJIO)}$	TRJIO input high width	200	—	120	—	40	—	ns
$t_{WL(TRJIO)}$	TRJIO input low width	200	—	120	—	40	—	ns

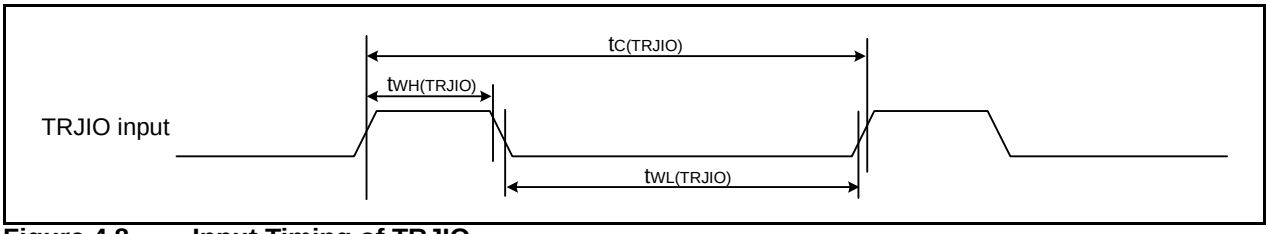
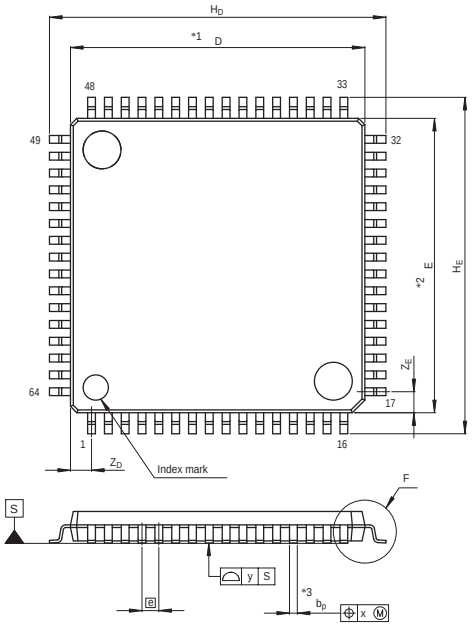
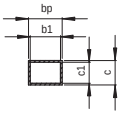


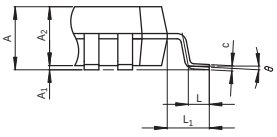
Figure 4.8 Input Timing of TRJIO

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-14x14-0.80	PLQP0064GA-A	64P6U-A/ —	0.7g





Terminal cross section



Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.32	0.37	0.42
b_1	—	0.35	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.8	—
x	—	—	0.20
y	—	—	0.10
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.3	0.5	0.7
L_1	—	1.0	—